



# Fast Core H

## Resin-Based Cored Wire Solder

### Features:

- Excellent Wetting Properties
- Produces Bright and Shiny Solder Joints
- Wide Process Window
- Clear, Hard Residues

### Description:

Fast Core H is a resin-based flux cored wire solder designed to offer excellent wetting characteristics, bright and shiny solder joints, and lead-free compatibility. This product is very active and is recommended for fast cycle time soldering. Fast Core H flux promotes good thermal transfer, offering excellent solder penetration into plated through holes or surface mount interconnections. Fast Core H produces low-to-medium, clear post-process residues. IPC flux classification for this material is REH1.

### Availability:

- Fast Core H is standard with a 2.5% flux core for tin-lead (2.5% flux core for lead-free) alloys.
- Fast Core H wire is available in Sn/Pb, Sn/Ag/Cu, SN100C<sup>®</sup> alloys.
- Standard spool sizes: ½ lb. for .010 and .015 diameters; 1 lb. for .020, .032, .040, .050, and .062 diameters.
- Packaging of ½ lb. and 1 lb. spools is standard in 12 lb. and 24 lb. cases.
- Other flux percentages, alloys, diameters and spool sizes may be available upon special request.

### Application:

- Solder iron tip temperature should be 350° - 400°C (650° - 750°F) for Sn63, Sn62 and Sn60 alloys, 370° - 425°C (700° - 800°F) for Sn/Ag and Sn/Ag/Cu alloys, 427° - 454°C (800°-850°F) for Sn10/Pb90 alloy, and 350° - 371°C (650°-700°F) for Sn43/Pb43/Bi14.
- Hold the solder iron at a 45° to 60° angle to the work surface.
- The solder iron should contact both the component lead and PCB pad surface.
- Solder and flux should flow onto both the lead and pad or lead and barrel to promote optimum flux activity to the joint being worked.
- If additional flux is needed, the use of AIM's RA301 flux is recommended. Operators should use an applicator capable of dispensing precise amounts of flux to eliminate over-saturation and excessive spread.

### Cleaning:

It is the decision of the user as to whether or not the cleaning of residues is required. If post-process cleaning is required, it is easiest if performed within a two to three hour period. A temperature of 100°-150°F normally is sufficient for removing residues. An in-line or other pressurized spray cleaning system is suggested, but is not required.

### Handling and Storage:

- Fast Core H wire has an indefinite shelf life when proper storage conditions are observed.
- Store product in a clean dry area away from moisture and sunlight.
- Do not freeze this product.

### Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying MSDS for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

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